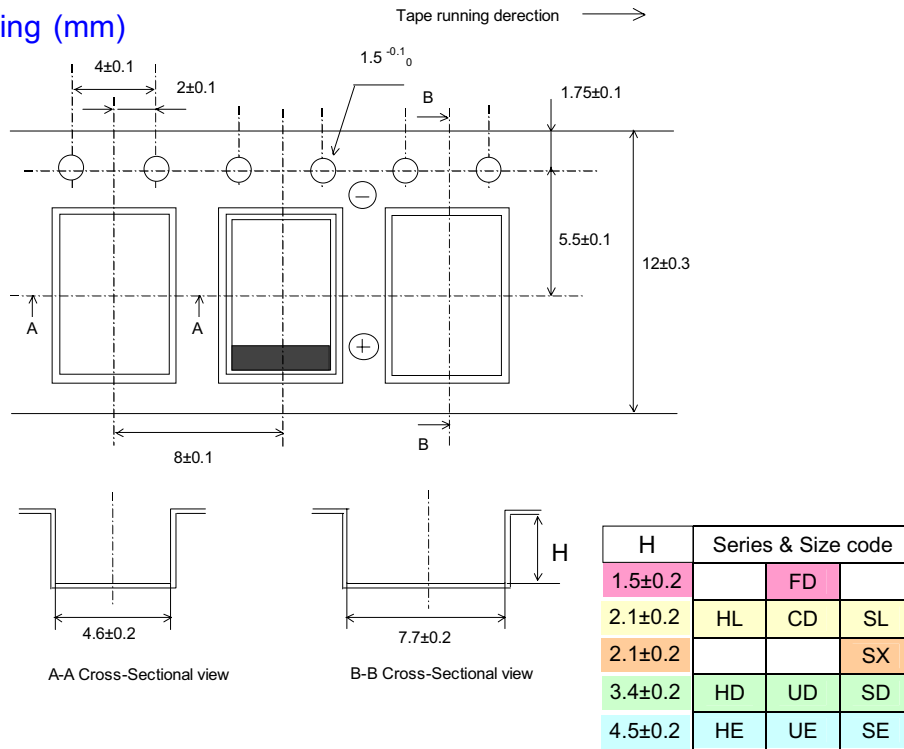


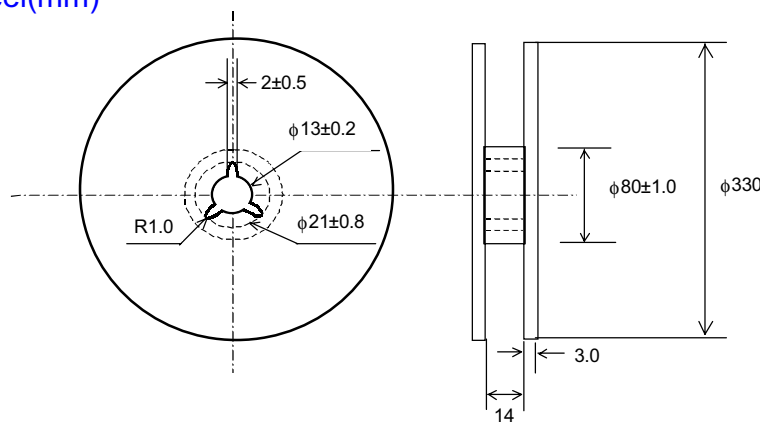


Packaging Specifications

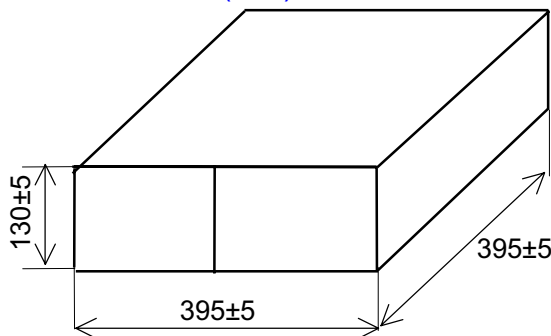
● Emboss taping (mm)



● Taping reel (mm)



● Packaging Box Dimensions (mm)



Packaging Specifications



Soldering Specifications

We recommend soldering be done according to the following maximum permissible reflow soldering temperature profile.

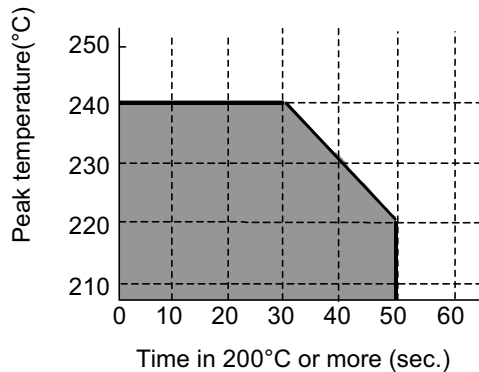
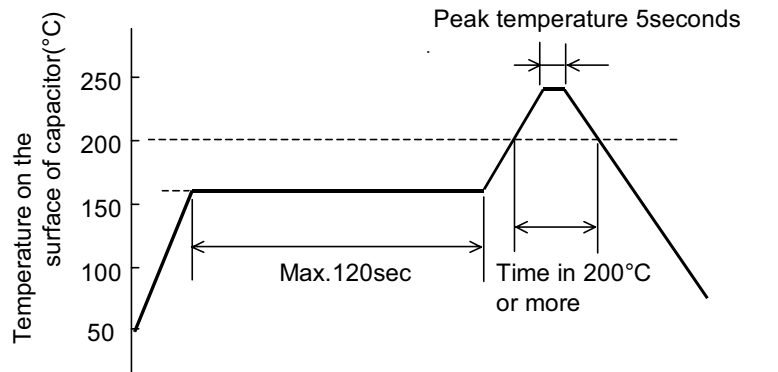
Reflow soldering

(This is a method to heat parts and the substrate by hot air or infrared furnace.)

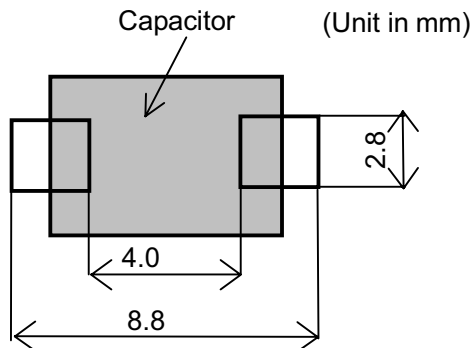
*Do not perform reflow soldering more than twice

Please be sure to perform the second reflow soldering within 5days.

(Please refer to item 5 of the Application Guidelines for the proper storing conditions prior to the second reflow)



Reference Land-pattern



Same land pattern design as a Tantalum electrolytic capacitor 7.3 x 4.3 mm product